

SEMITRANS[®] 5

Trench IGBT Modules

SKM300MLI066TAT

Features

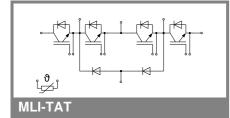
- Homogeneous Si
- Trench = Trenchgate technology
- V_{CE(sat)} with positive temperature coefficient
- Integrated NTC temperature sensor

Typical Applications*

- UPS
- 3 Level Inverter

Remarks

- Case temperature limited to T_c =125°C max
- Recommended T_{op} = -40..+150°C for IGBT; T_{op}=-40..+125°C for diod
- T_{op}=-40..+125°C for diode
 T_{vj} is intended as absolute maximum rating, limited by diode
- Fig.2 is referred to IGBT current capability



Absolute Maximum Ratings T _{case} = 25°C, unless otherwise specified						
Symbol	Conditions		Values	Units		
IGBT						
V _{CES}	T _j = 25 °C		600	V		
I _C	T _j = 175 °C	T _c = 25 °C	400	А		
		T _c = 80 °C	300	А		
I _{CRM}	I _{CRM} =2xI _{Cnom}		600	А		
V_{GES}			± 20	V		
t _{psc}	$\label{eq:V_CC} \begin{array}{l} V_{CC} \texttt{=} \texttt{360 V}; \ V_{GE} \leq \texttt{15 V}; \\ V_{CES} \texttt{<} \texttt{600 V} \end{array}$	T _j = 150 °C	6	μs		
Inverse D	Diode					
I _F	T _j = 150 °C	T _c = 25 °C	324	A		
		T _c = 80 °C	211	Α		
I _{FRM}	I _{FRM} =2xI _{Fnom}		420	А		
I _{FSM}	t _p = 10 ms; half sine wave	T _j = 150 °C	2100	А		
Freewhee	eling Diode					
I _F	T _j = 150 °C	T _c = 25 °C	324	А		
		T _c = 80 °C	211	A		
I _{FRM}	I _{FRM} =2xI _{Fnom}		420	А		
I _{FSM}	t _p = 10 ms; half sine wave	T _j = 150 °C	2100	А		
Module						
I _{t(RMS)}			500	А		
T _{vj}			- 40 + 150	°C		
T _{stg}			- 40 + 125	°C		
V _{isol}	AC, 1 min.		2500	V		

Characteristics T _{ca}		T _{case} =	= 25°C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units	
IGBT	_						
V _{GE(th)}	V_{GE} = V_{CE} , I_C = 4,8 mA		5	5,8	6,5	V	
I _{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}	T _j = 25 °C			0,5	mA	
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V	T _j = 25 °C			1200	nA	
V _{CE0}		T _j = 25 °C		0,9	1	V	
		T _j = 150 °C		0,85	0,9	V	
r _{CE}	V _{GE} = 15 V	T _i = 25°C		1,8	3	mΩ	
		T _j = 150°C		2,7	3,8	mΩ	
V _{CE(sat)}	I _{Cnom} = 300 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		1,45	1,9	V	
		T _j = 150°C _{chiplev.}		1,7	2,1	V	
C _{ies}				18,4		nF	
C _{oes}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		1,14		nF	
C _{res}				0,54		nF	
Q_{G}	V _{GE} = -15V+15V			3900		nC	
R _{Gint}	T _j = °C			1		Ω	
t _{d(on)}				140		ns	
t _r E _{on}	R _{Gon} = 2,2 Ω	V _{CC} = 300V		89		ns	
Eon	di/dt = 3400 A/µs	I _C = 300A		3,5		mJ	
^L d(off)	R_{Goff} = 2,2 Ω	T _j = 125 °C		433		ns	
t _f	di/dt = 3400 A/µs	V _{GE} = 15V/+15V		116		ns	
E _{off}				10,1		mJ	
R _{th(j-c)}	per IGBT	•		0,15		K/W	



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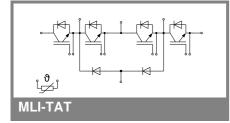
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Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	ode					
$V_F = V_{EC}$	I_{Fnom} = 245 A; V_{GE} = 0 V	T _j = 25 °C _{chiplev.}		1,35	1,6	V
		T _j = 125 °C _{chiplev.}		1,35	1,6	V
V _{F0}		$T_j = 125 \ ^\circ C_{chiplev.}$ $T_j = 25 \ ^\circ C$		1	1,1	V
		T _j = 125 °C		0,9	1	V
r _F		T _j = 25 °C		1,42	2	mΩ
		T _j = 125 °C		1,8	2,4	mΩ
I _{RRM} Q _{rr}	I _F = 245 A	T _j = 125 °C				A µC
E _{rr}	V _{GE} = -8 V; V _{CC} = 300 V					mJ
R _{th(j-c)D}	per diode			0,28		K/W
	eling diode (Neutral (Clamp Diode)				
$V_F = V_{EC}$	I _{Fnom} = 245 A; V _{GE} = 0 V	T _j = 25 °C _{chiplev.}		1,35	1,6	V
		T _j = 125 °C _{chiplev.}		1,35	1,6	V
V _{F0}		T _j = 25 °C		1	1,1	V
		T _j = 125 °C		0,9	1	V
r _F		T _j = 25 °C		1,42	2	V
		T _j = 125 °C		1,8	2,4	V
IRRM	I _F = 300 A	T _j = 125 °C		194		A
Q _{rr}	di/dt = 3400 A/µs			13		μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 300 V			4		mJ
R _{th(j-c)FD}	per diode			0,28		K/W
R _{th(c-s)}	per module				0,038	K/W
M _s	to heat sink M6		3		5	Nm
M _t	to terminals M6		2,5		5	Nm
w					310	g
Temperat	ture sensor					
R ₁₀₀	T _s =100°C (R ₂₅ =5kΩ)			493±5%		Ω
						к

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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